



BUK9J0R9-40H

N-channel 40 V, 0.9 mΩ logic level MOSFET in LFPAK56E

10 January 2024

Product data sheet

1. General description

Automotive qualified N-channel MOSFET using the latest Trench 9 low ohmic superjunction technology, housed in an enhanced LFPAK56E package. This product has been fully designed and qualified to meet AEC-Q101 requirements delivering high performance and endurance.

2. Features and benefits

- Fully automotive qualified to AEC-Q101:
 - 175 °C rating suitable for thermally demanding environments
- Trench 9 Superjunction technology:
 - Reduced cell pitch enables enhanced power density and efficiency with lower R_{DSon} in same footprint
 - Improved SOA and avalanche capability compared to standard TrenchMOS
 - Tight $V_{GS(th)}$ limits enable easy paralleling of MOSFETs
- LFPAK Gull Wing leads:
 - High Board Level Reliability absorbing mechanical stress during thermal cycling, unlike traditional QFN packages
 - Visual (AOI) soldering inspection, no need for expensive x-ray equipment
 - Easy solder wetting for good mechanical solder joint
- LFPAK copper clip technology:
 - Improved reliability, with reduced R_{th} and R_{DSon}
 - Increases maximum current capability and improved current spreading

3. Applications

- 12 V automotive systems
- Motors, lamps and solenoid control
- Start-Stop micro-hybrid applications
- Transmission control
- Ultra high performance power switching

4. Quick reference data

Table 1. Quick reference data

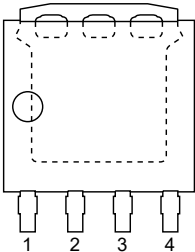
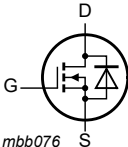
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$25\text{ °C} \leq T_j \leq 175\text{ °C}$		-	-	40	V
I_D	drain current	$V_{GS} = 10\text{ V}$; $T_{mb} = 25\text{ °C}$; Fig. 2	[1]	-	-	220	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C}$; Fig. 1		-	-	500	W
Static characteristics							
R_{DSon}	drain-source on-state resistance	$V_{GS} = 10\text{ V}$; $I_D = 25\text{ A}$; $T_j = 25\text{ °C}$; Fig. 11		0.53	0.82	0.94	mΩ

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Dynamic characteristics						
Q_{GD}	gate-drain charge	$I_D = 25\text{ A}$; $V_{DS} = 20\text{ V}$; $V_{GS} = 4.5\text{ V}$; Fig. 13 ; Fig. 14	-	12.7	25.3	nC
Source-drain diode						
Q_r	recovered charge	$I_S = 25\text{ A}$; $dI_S/dt = -100\text{ A/}\mu\text{s}$; $V_{GS} = 0\text{ V}$; $V_{DS} = 20\text{ V}$; $T_j = 25\text{ }^\circ\text{C}$ [2]	-	52.6	-	nC
S	softness factor	$I_S = 25\text{ A}$; $dI_S/dt = -100\text{ A/}\mu\text{s}$; $V_{GS} = 0\text{ V}$; $V_{DS} = 20\text{ V}$; $T_j = 25\text{ }^\circ\text{C}$; Fig. 17	-	0.77	-	

- [1] 220A continuous current has been successfully demonstrated during application tests. Practically the current will be limited by PCB, thermal design and operating temperature.
- [2] includes capacitive recovery

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	 LPAK56E; Power-SO8 (SOT1023)	 mbb076
2	S	source		
3	S	source		
4	G	gate		
mb	D	mounting base; connected to drain		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BUK9J0R9-40H	LPAK56E; Power-SO8	plastic, single-ended surface-mounted package (LPAK56); 4 leads; 1.27 mm pitch	SOT1023

7. Marking

Table 4. Marking codes

Type number	Marking code
BUK9J0R9-40H	90H940E

8. Limiting values

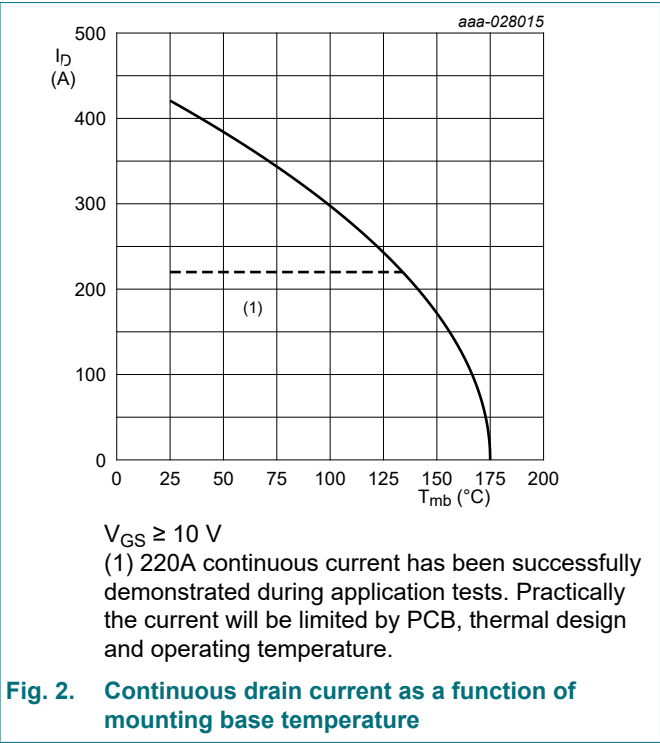
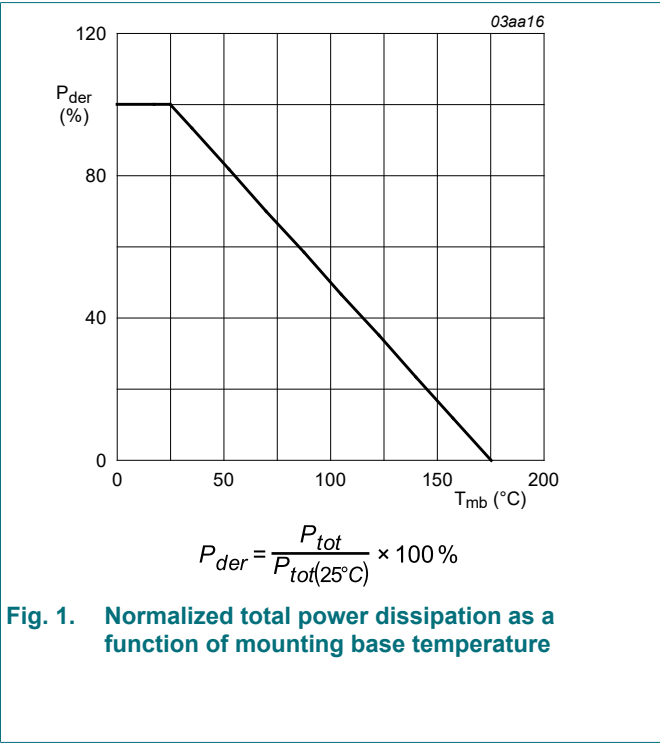
Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage	$25\text{ }^\circ\text{C} \leq T_j \leq 175\text{ }^\circ\text{C}$	-	40	V
V_{GS}	gate-source voltage	DC; $T_j \leq 175\text{ }^\circ\text{C}$	-10	16	V

Symbol	Parameter	Conditions		Min	Max	Unit
P _{tot}	total power dissipation	T _{mb} = 25 °C; Fig. 1		-	500	W
I _D	drain current	V _{GS} = 10 V; T _{mb} = 25 °C; Fig. 2	[1]	-	220	A
		V _{GS} = 10 V; T _{mb} = 100 °C; Fig. 2	[1]	-	220	A
I _{DM}	peak drain current	pulsed; t _p ≤ 10 μs; T _{mb} = 25 °C; Fig. 3		-	600	A
T _{stg}	storage temperature			-55	175	°C
T _j	junction temperature			-55	175	°C
Source-drain diode						
I _S	source current	T _{mb} = 25 °C	[2]	-	165	A
I _{SM}	peak source current	pulsed; t _p ≤ 10 μs; T _{mb} = 25 °C		-	600	A
Avalanche ruggedness						
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	I _D = 160 A; V _{sup} ≤ 40 V; R _{GS} = 50 Ω; V _{GS} = 10 V; T _{j(init)} = 25 °C; unclamped; Fig. 4	[3] [4]	-	290	mJ

- [1] 220A continuous current has been successfully demonstrated during application tests. Practically the current will be limited by PCB, thermal design and operating temperature.
- [2] 165A continuous current has been successfully demonstrated during application tests. Practically the current will be limited by PCB, thermal design and operating temperature.
- [3] Single-pulse avalanche rating limited by maximum junction temperature of 175 °C.
- [4] Refer to application note AN10273 for further information.



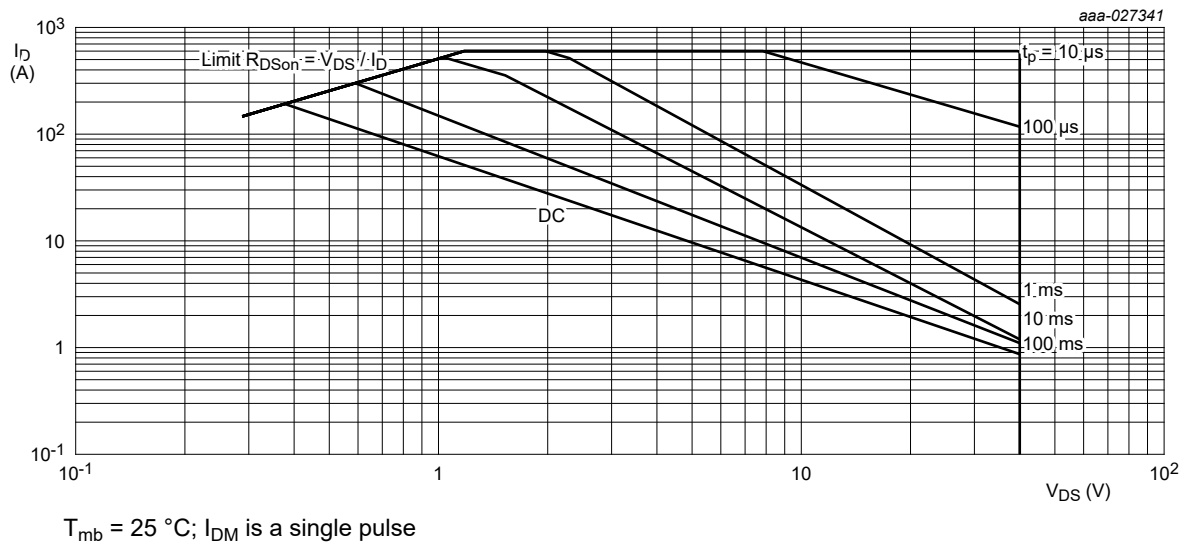


Fig. 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

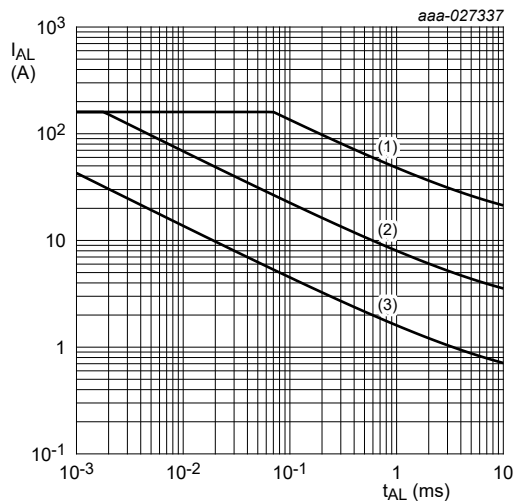


Fig. 4. Avalanche rating; avalanche current as a function of avalanche time

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 5	-	0.21	0.3	K/W

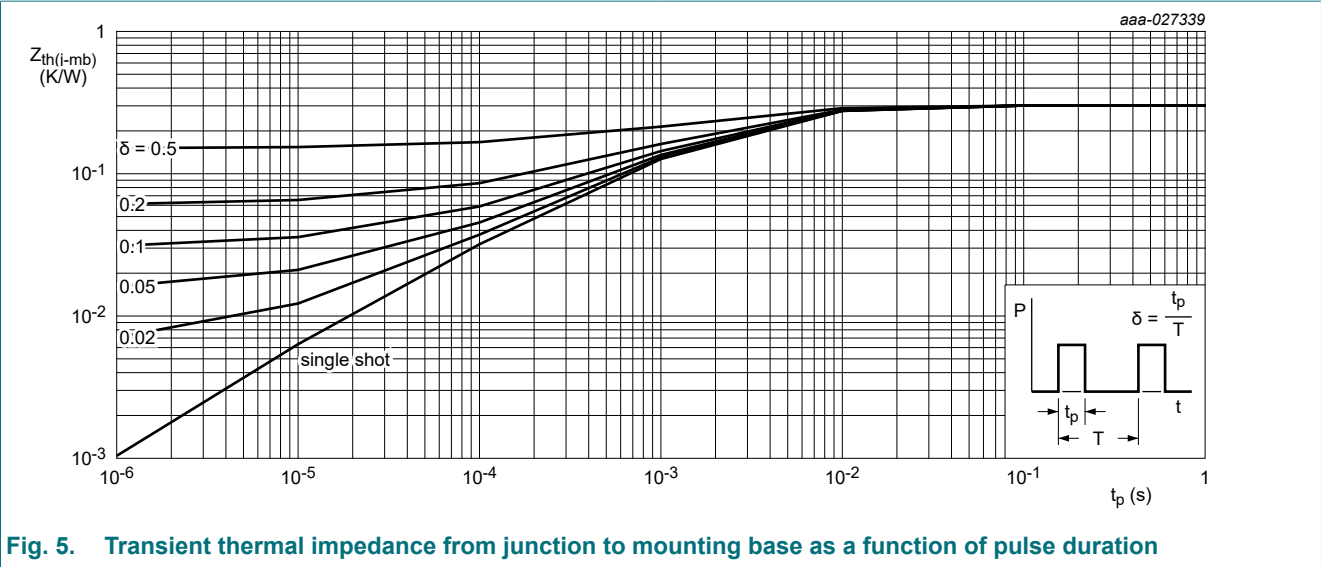


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V _{(BR)DSS}	drain-source breakdown voltage	I _D = 250 μA; V _{GS} = 0 V; T _J = 25 °C	40	43	-	V
		I _D = 250 μA; V _{GS} = 0 V; T _J = -40 °C	-	40.5	-	V
		I _D = 250 μA; V _{GS} = 0 V; T _J = -55 °C	36	40	-	V
V _{GS(th)}	gate-source threshold voltage	I _D = 1 mA; V _{DS} =V _{GS} ; T _J = 25 °C; Fig. 9 ; Fig. 10	1.35	1.66	2.05	V
		I _D = 1 mA; V _{DS} =V _{GS} ; T _J = 175 °C; Fig. 10	0.6	-	-	V
		I _D = 1 mA; V _{DS} =V _{GS} ; T _J = -55 °C; Fig. 10	-	-	2.5	V
I _{DSS}	drain leakage current	V _{DS} = 40 V; V _{GS} = 0 V; T _J = 25 °C	-	0.4	5	μA
		V _{DS} = 16 V; V _{GS} = 0 V; T _J = 125 °C	-	3.2	25	μA
		V _{DS} = 40 V; V _{GS} = 0 V; T _J = 175 °C	-	405	1000	μA
I _{GSS}	gate leakage current	V _{GS} = 16 V; V _{DS} = 0 V; T _J = 25 °C	-	2	100	nA
		V _{GS} = -10 V; V _{DS} = 0 V; T _J = 25 °C	-	2	100	nA

N-channel 40 V, 0.9 mΩ logic level MOSFET in LPAK56E

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
R _{DSon}	drain-source on-state resistance	V _{GS} = 10 V; I _D = 25 A; T _J = 25 °C; Fig. 11		0.53	0.82	0.94	mΩ
		V _{GS} = 10 V; I _D = 25 A; T _J = 105 °C; Fig. 12		0.79	1.17	1.48	mΩ
		V _{GS} = 10 V; I _D = 25 A; T _J = 125 °C; Fig. 12		0.87	1.29	1.64	mΩ
		V _{GS} = 10 V; I _D = 25 A; T _J = 175 °C; Fig. 12		1.1	1.63	2.05	mΩ
		V _{GS} = 4.5 V; I _D = 25 A; T _J = 25 °C; Fig. 11		0.68	0.97	1.2	mΩ
		V _{GS} = 4.5 V; I _D = 25 A; T _J = 105 °C; Fig. 12		1	1.47	1.9	mΩ
		V _{GS} = 4.5 V; I _D = 25 A; T _J = 125 °C; Fig. 12		1.1	1.62	2.1	mΩ
		V _{GS} = 4.5 V; I _D = 25 A; T _J = 175 °C; Fig. 12		1.4	2.03	2.6	mΩ
R _G	gate resistance	f = 1 MHz; T _J = 25 °C		0.42	1.04	2.6	Ω
Dynamic characteristics							
Q _{G(tot)}	total gate charge	I _D = 25 A; V _{DS} = 20 V; V _{GS} = 10 V; Fig. 13 ; Fig. 14		-	120	168	nC
		I _D = 25 A; V _{DS} = 20 V; V _{GS} = 4.5 V; Fig. 13 ; Fig. 14		-	54.2	76	nC
Q _{GS}	gate-source charge			-	20.2	30.2	nC
Q _{GD}	gate-drain charge			-	12.7	25.3	nC
C _{iss}	input capacitance	V _{DS} = 25 V; V _{GS} = 0 V; f = 1 MHz; T _J = 25 °C; Fig. 15		-	8977	12568	pF
C _{oss}	output capacitance			-	1549	2168	pF
C _{rss}	reverse transfer capacitance			-	346	760	pF
t _{d(on)}	turn-on delay time	V _{DS} = 20 V; R _L = 0.8 Ω; V _{GS} = 4.5 V; R _{G(ext)} = 5 Ω		-	45.4	-	ns
t _r	rise time			-	46.2	-	ns
t _{d(off)}	turn-off delay time			-	59.2	-	ns
t _f	fall time			-	32.6	-	ns
Source-drain diode							
V _{SD}	source-drain voltage	I _S = 25 A; V _{GS} = 0 V; T _J = 25 °C; Fig. 16		-	0.76	1.2	V
t _{rr}	reverse recovery time	I _S = 25 A; dI _S /dt = -100 A/μs; V _{GS} = 0 V; V _{DS} = 20 V; T _J = 25 °C		-	44.6	-	ns
Q _r	recovered charge		[1]	-	52.6	-	nC
S	softness factor	I _S = 25 A; dI _S /dt = -100 A/μs; V _{GS} = 0 V; V _{DS} = 20 V; T _J = 25 °C; Fig. 17		-	0.77	-	
		I _S = 25 A; dI _S /dt = -500 A/μs; V _{GS} = 0 V; V _{DS} = 20 V; T _J = 25 °C; Fig. 17		-	0.67	-	

[1] includes capacitive recovery

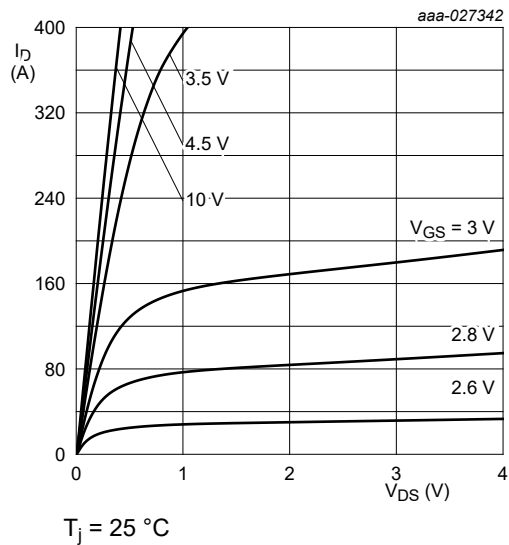


Fig. 6. Output characteristics; drain current as a function of drain-source voltage; typical values

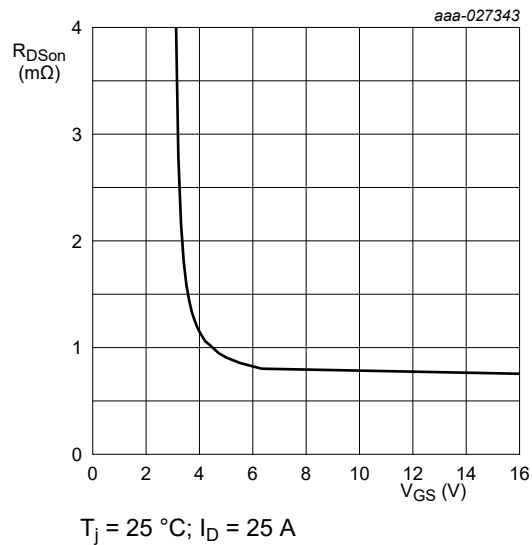


Fig. 7. Drain-source on-state resistance as a function of gate-source voltage; typical values

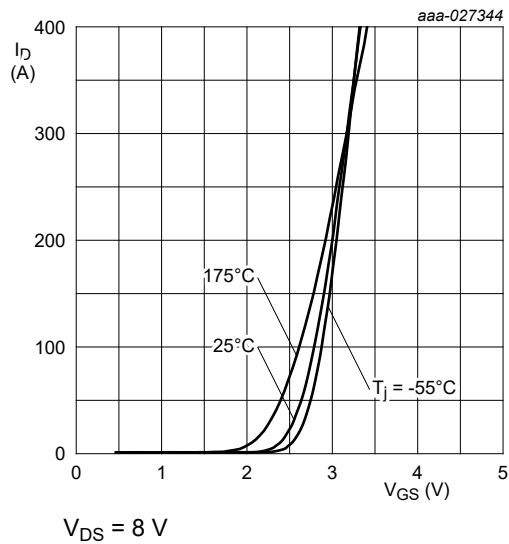


Fig. 8. Transfer characteristics; drain current as a function of gate-source voltage; typical values

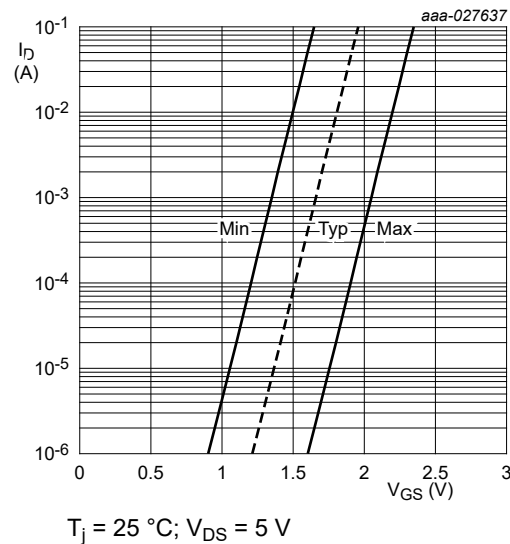


Fig. 9. Sub-threshold drain current as a function of gate-source voltage

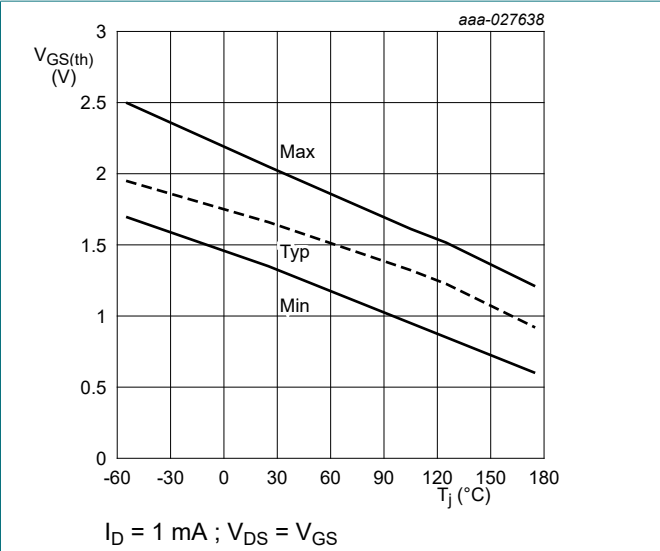


Fig. 10. Gate-source threshold voltage as a function of junction temperature

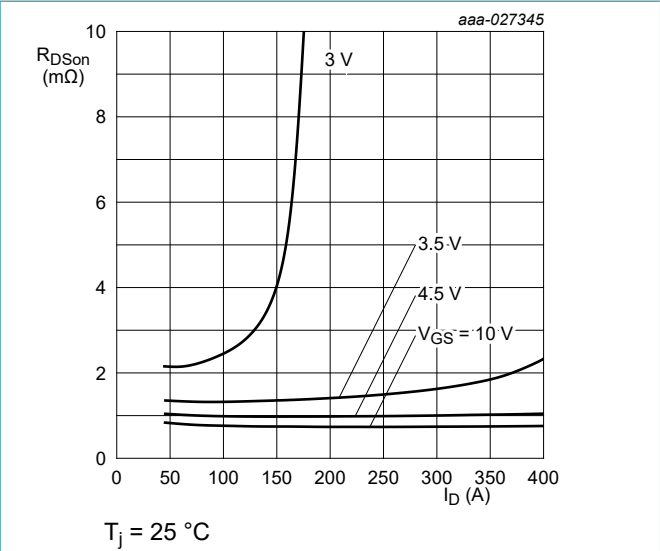


Fig. 11. Drain-source on-state resistance as a function of drain current; typical values

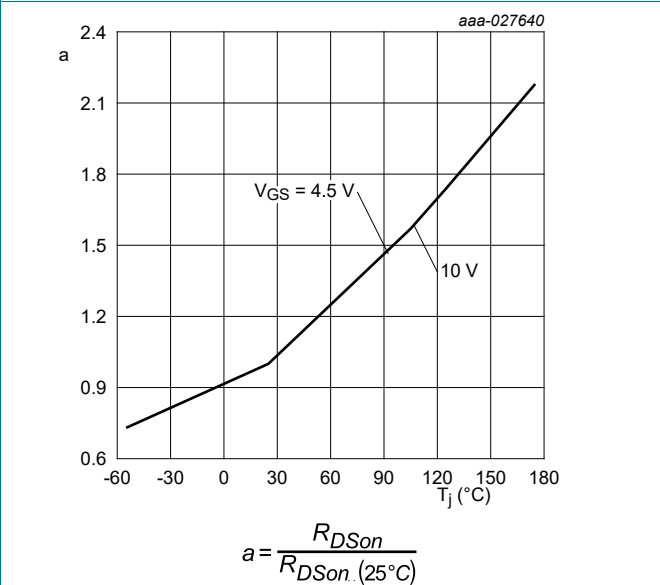


Fig. 12. Normalized drain-source on-state resistance factor as a function of junction temperature

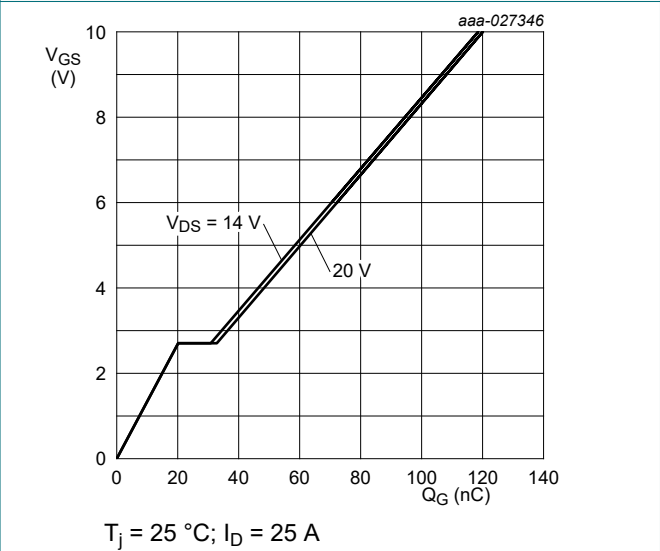


Fig. 13. Gate-source voltage as a function of gate charge; typical values

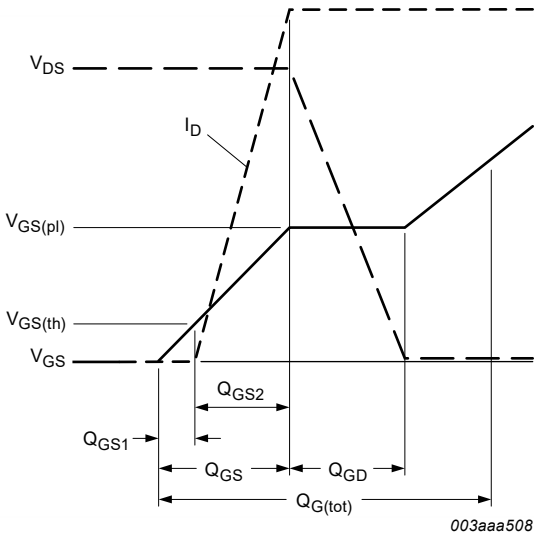


Fig. 14. Gate charge waveform definitions

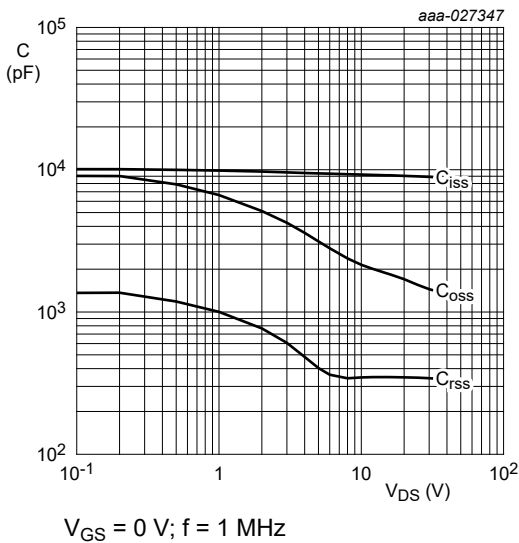


Fig. 15. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

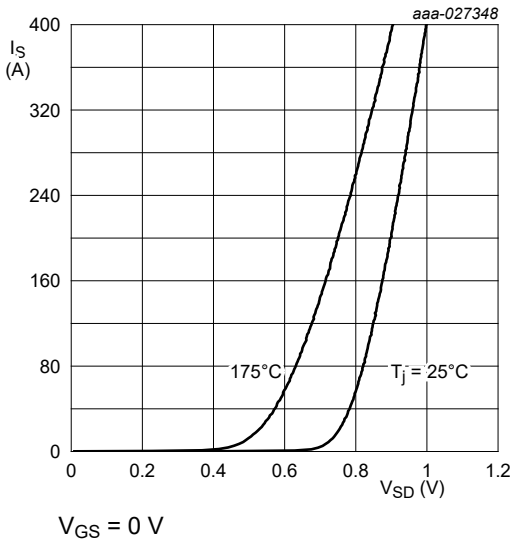


Fig. 16. Source-drain (diode forward) current as a function of source-drain (diode forward) voltage; typical values

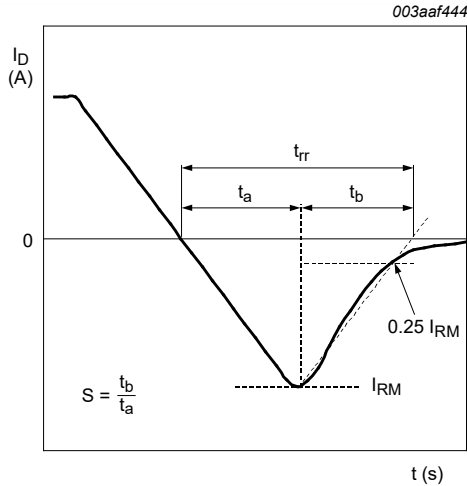


Fig. 17. Reverse recovery timing definition

11. Package outline

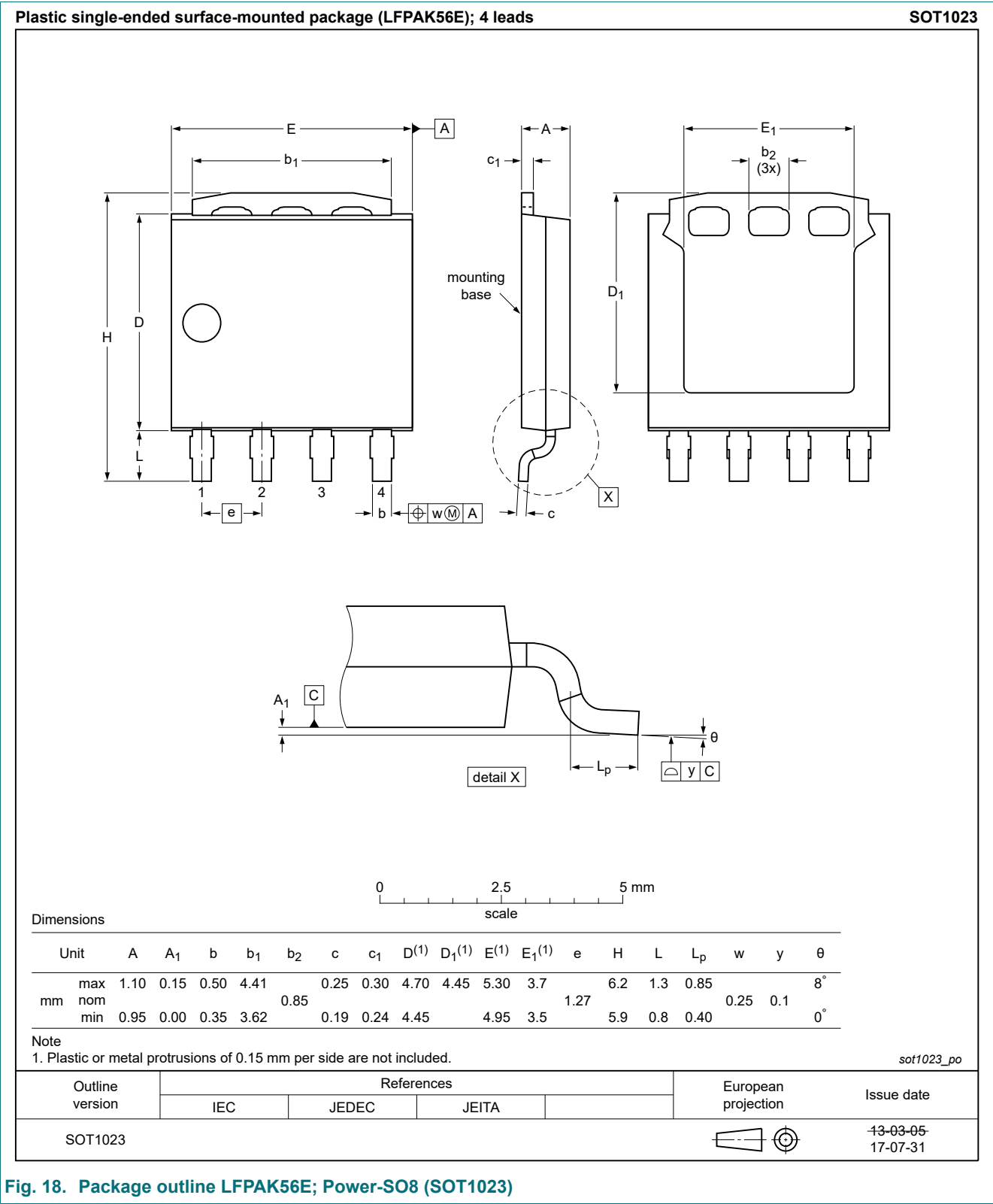
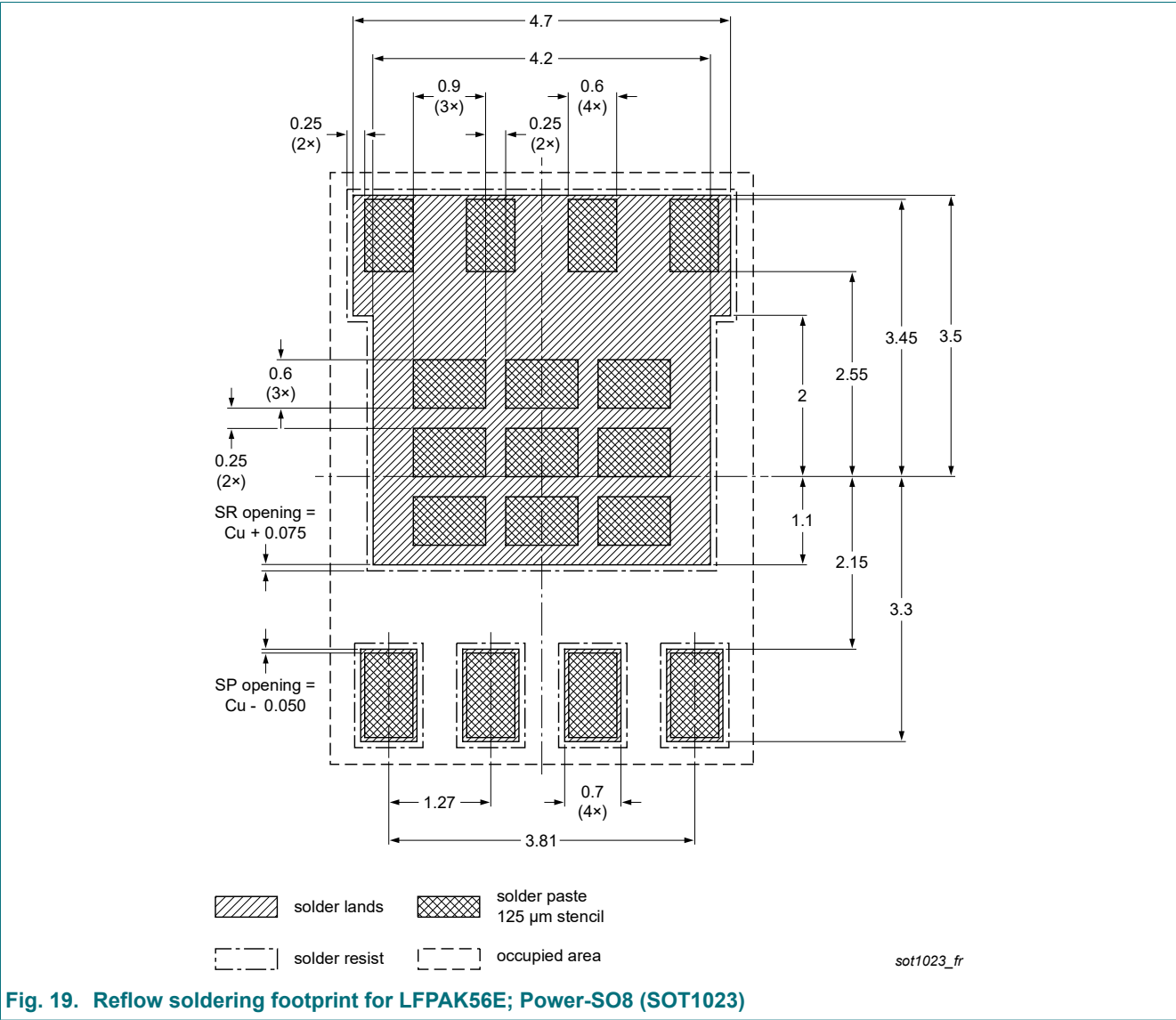


Fig. 18. Package outline LPAK56E; Power-SO8 (SOT1023)

12. Soldering



13. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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